

Declaration for Patent Application

特許出願宣言書

Japanese Language Declaration

私は、下欄に氏名を記載した発明者として、以下のとおり宣言する：

私の住所、郵便宛先および国籍は、下欄に氏名に続いて記載したとおりであり、下記名称の発明に関し、特許請求の範囲に記載した特許を求める主題の本来の、最初にして唯一の発明者である（一人の氏名のみが下欄に記載されている場合）か、もしくは本来の、最初にして共同の発明者である（複数の氏名が下欄に記載されている場合）と信じ、

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name. I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled:

MANUFACTURING METHOD OF SEMICONDUCTOR DEVICE AND SUBSTRATE

PROCESSING APPARATUS

その明細書を
(該当するものにチェック)

☐ ここに添付する。

☐ _____年____月____日に

出願番号第_____として提出され、

_____年____月____日に補正し、
(該当する場合)

私は、前記のとおり補正した特許請求の範囲を含む前記明細書の内容を検討し、理解したことを陳述する。

私は、連邦施行規則第 37 章第 1 条第 56 項に従い、本願の特許性の有無について重要な情報を開示すべき義務を有することを認める。

私は、米国法第 35 章第 119 条に基づく下記の外国特許出願もしくは発明者証出願の外国優先権利益を主張し、さらに優先権の主張に係わる基礎出願の提出日前の提出日を有する外国特許出願もしくは発明者証出願および/もしくは米国仮出願を以下に明記する：

the specification of which
(check one)

☐ is attached hereto.

☒ was filed on January 21, 2005 as

Application Serial No. PCT/JP2005/000751

and was amended on _____
(if applicable)

I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose information which is material to patentability as defined in Title 37, Code of Federal Regulations, §1.56.

I hereby claim foreign priority benefits under Title 35, United States Code §119 of any foreign application(s) for patent or inventor's certificate listed below and/or any U.S. provisional application(s) listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:

Prior foreign and/or provisional applications
先行外国出願/仮出願

Priority claimed
優先権の主張

<u>2004-012885</u> (Number/番号)	<u>JAPAN</u> (Country/国名)	<u>21/1/04</u> (Day/Month/Year Filed/提出年月日)	<input checked="" type="checkbox"/> (Yes/はい)	<input type="checkbox"/> (No/いいえ)
<u> </u> (Number/番号)	<u> </u> (Country/国名)	<u> </u> (Day/Month/Year Filed/提出年月日)	<input type="checkbox"/> (Yes/はい)	<input type="checkbox"/> (No/いいえ)
<u> </u> (Number/番号)	<u> </u> (Country/国名)	<u> </u> (Day/Month/Year Filed/提出年月日)	<input type="checkbox"/> (Yes/はい)	<input type="checkbox"/> (No/いいえ)
<u> </u> (Number/番号)	<u> </u> (Country/国名)	<u> </u> (Day/Month/Year Filed/提出年月日)	<input type="checkbox"/> (Yes/はい)	<input type="checkbox"/> (No/いいえ)

私は、米国法第 35 章第 120 条に基づく下記の米国特許出願の利益を主張し、本願の特許請求の範囲各項に記載の主題が米国法第 35 章第 112 条の第 1 段落に規定の態様で先の米国出願に開示されていない限度において、先の出願の提出日と本願の国内提出日もしくは P C T 国際出願提出日の間に公表された連邦施行規則第 37 章第 1 条第 56 項に記載の重要な情報を開示すべき義務を有することを認める。

I hereby claim the benefit under Title 35, United States code, §120 of any United States application(s) listed below and, in so far as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, §112. I acknowledge the duty to disclose material information as defined in Title 37, Code of Federal Regulations, §1.56 which occurred between the filing date of the prior application and the national or PCT international filing date of this application:

<u> </u> (Application Serial No./出願番号)	<u> </u> (Filing Date/提出日)	<u> </u> (Status: Patented, Pending, abandoned/ 現状：特許成立、係属中、放棄済み)
<u> </u> (Application Serial No./出願番号)	<u> </u> (Filing Date/提出日)	<u> </u> (Status: Patented, Pending, abandoned/ 現状：特許成立、係属中、放棄済み)

私は、ここに自己の知識にもとづいて行った陳述がすべて真実であり、自己の有する情報および信ずるところに従って行った陳述が真実であると信じ、さらに故意に虚偽の陳述等を行った場合、米国法第 18 章第 1001 条により、罰金もしくは禁錮に処せられるか、またはこれらの刑が併科され、またかかる故意による虚偽の陳述が本願ないし本願に対して付与される特許の有効性を損なうことがあることを認識して、以上の陳述を行ったことを宣言する。

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true: and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Send Correspondence To/書類送付先:

OLIFF & BERRIDGE, PLC
CUSTOMER NUMBER 25944
Telephone: (703) 836-6400

Direct Telephone Calls To (name and telephone number)/直通電話連絡先(名称および電話番号):

Full name of sole or first inventor/単独または第一発明者の氏名 Atsushi SANO	
Inventor's signature/同発明者の署名 <i>Atsushi Sano</i>	Date/日付 <i>April 12, 2006</i>
Residence/住所 Toyama, Japan	
Citizenship/国籍 JAPAN	
Post Office Address/郵便宛先 c/o HITACHI KOKUSAI ELECTRIC INC. 1, Yasuuchi 2-chome, Yatsuo-machi, Toyama-shi, Toyama 939-2393 JAPAN	
Full name of second joint inventor (if any)/第二共同発明者の氏名(該当する場合) Sadayoshi HORII	
Second inventor's signature/第二発明者の署名 <i>Sadayoshi Horii</i>	Date/日付 <i>April 12, 2006</i>
Residence/住所 Toyama, Japan	
Citizenship/国籍 JAPAN	
Post Office Address/郵便宛先 c/o HITACHI KOKUSAI ELECTRIC INC. 1, Yasuuchi 2-chome, Yatsuo-machi, Toyama-shi, Toyama 939-2393 JAPAN	
Full name of third joint inventor (if any)/第三共同発明者の氏名(該当する場合) Hideharu ITATANI	
Third inventor's signature/第三発明者の署名 <i>Hideharu Itatani</i>	Date/日付 <i>April 11, 2006</i>
Residence/住所 Toyama, Japan	
Citizenship/国籍 JAPAN	
Post Office Address/郵便宛先 c/o HITACHI KOKUSAI ELECTRIC INC. 1, Yasuuchi 2-chome, Yatsuo-machi, Toyama-shi, Toyama 939-2393 JAPAN	
Full name of fourth joint inventor (if any)/第四共同発明者の氏名(該当する場合) Masayuki ASAI	
Fourth inventor's signature/第四発明者の署名 <i>Masayuki Asai</i>	Date/日付 <i>April 12, 2006</i>
Residence/住所 Toyama, Japan	
Citizenship/国籍 JAPAN	
Post Office Address/郵便宛先 c/o HITACHI KOKUSAI ELECTRIC INC. 1, Yasuuchi 2-chome, Yatsuo-machi, Toyama-shi, Toyama 939-2393 JAPAN	

PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Atsushi SANO et al.

Application No.: 10/574,571

Filed: April 28, 2006

Docket No.: 127570

For: MANUFACTURING METHOD OF SEMICONDUCTOR DEVICE AND SUBSTRATE
PROCESSING APPARATUS

**TRANSMITTAL OF POWER OF ATTORNEY AND
STATEMENT UNDER 37 CFR § 3.73(b)**

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

Submitted herewith is a Power of Attorney from the Assignee.

In compliance with 37 CFR §3.73(b), the undersigned hereby states that HITACHI KOKUSAI ELECTRIC INC. is the assignee of the entire right, title and interest in the patent application identified above by virtue of an assignment from the inventors of the patent application identified above. A copy of the assignment is attached hereto and is concurrently being submitted for recordation.

The undersigned is authorized to act on behalf of the assignee.

In accordance with 37 CFR §1.36(a), submission of this Power of Attorney revokes any powers of attorney previously given.

**ALL CORRESPONDENCE IN CONNECTION WITH THIS APPLICATION SHOULD
BE SENT TO OLIFF & BERRIDGE, PLC, CUSTOMER NO. 25944, TELEPHONE
(703) 836-6400.**

Respectfully submitted,



James A. Oliff
Registration No. 27,075

Linda M. Saltiel
Registration No. 51,122

JAO:LMS/nxy

Date: April 28, 2006

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE
米国特許商標庁において

In re the Application of/出願人名

Group Art Unit/グループ技術ユニット名:

Application No./出願番号:

Examiner/審査官:

Filed/出願日:

Docket No./整理番号:

For/発明の名称: MANUFACTURING METHOD OF SEMICONDUCTOR DEVICE AND SUBSTRATE PROCESSING APPARATUS

SPECIFIC POWER OF ATTORNEY

特定委任状

Japanese Language Specific Power of AttorneyCommissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450下記段落の理由により、上記特許出願の全ての権利、所有権、および
び権益を有する(該当するものにチェック)☐ 所有者である (会社名)記入)もしくは、☐ 共同所有者である

(会社名記入)は、

HITACHI KOKUSAI ELECTRIC INC.

(Check one)

☐ owner or ☐ co-owner of the entire right, title and interest in the above
patent application by virtue of:

(該当するものにチェック)

a. ☐ 発明者であり、もしくはb. ☐ 譲渡者であり

(該当するものにチェック)

i. ☐ コピー添付、もしくはii. ☐ 米国特許庁マイクロフィルム記録のリール番号

、駒番号 に記録されており、

(Check one)

a. ☐ being an inventor, orb. ☐ an Assignment

(Check one)

i. ☐ copy attached, orii. ☐ recorded at Reel

Frame of the Patent Office microfilm records,

上記所有者は、この出願、かつその全ての継続出願および分割出願を
遂行するために、かつ米国特許商標庁において全ての業務を執行する
ために、記録上の弁護士として、Oliff & Berridge, PLC顧客番号
25944と関連した特許執行者をここに任命する。hereby appoints the patent practitioners associated with Oliff & Berridge,
PLC Customer No. 25944 as attorneys of record to prosecute this application
and all continuations and divisions thereof, and to transact all business in the
Patent and Trademark Office.下記署名は、所有権の一連を顧み、前記所有権が所有者にあること
を確認する。下記署名人は、所有者として、もしくは所有者の代理と
して、任務を行う権限を有する。この出願に関するすべての連絡事項は、Oliff & Berridge, PLC、顧客
番号25944、電話番号(703) 836-6400に送付すること。The undersigned has reviewed the chain of title and confirms that
the aforesaid title is in the owner. The undersigned is authorized to execute
this document as or on behalf of the owner.ALL CORRESPONDENCE IN CONNECTION WITH THIS
APPLICATION SHOULD BE SENT TO OLIFF & BERRIDGE, PLC,
CUSTOMER NO. 25944, TELEPHONE (703) 836-6400.

Date/日付

Signature/署名

Masanori Kaneko

Typed Name/タイプライターによる氏名

Title/役職名:

Corporate Officer

General Manager

IPR & Licensing Division

(if acting on behalf of an Owner)

(所有者の代理を務める場合)

ASSIGNMENT

(1-8) **Insert Name(s) of Inventor(s)**

(1) Atsushi SANO (5) _____

(2) Sadayoshi HORII (6) _____

(3) Hideharu ITATANI (7) _____

(4) Masayuki ASAI (8) _____

In consideration of the sum of one dollar (\$1.00) and other good and valuable consideration paid to each of the undersigned, each undersigned agrees to assign, and hereby does assign, transfer and set over to

(9) **Insert Name of Assignee** (9) HITACHI KOKUSAI ELECTRIC INC.

(10) **Insert Address of Assignee** (10) 14-1, Soto-Kanda 4-chome, Chiyoda-ku, Tokyo 101-8980, Japan

(hereinafter designated as the Assignee) and Assignee's heirs, successors, assigns and legal representatives, the entire right, title and interest for the United States of America as defined in 35 U.S.C. §100, in the invention, and in all applications for patent including any and all provisional, non-provisional, divisional, continuation, international, confirmation, substitute and reissue application(s), and all Letters Patent, extensions, reissues and reexamination certificates that may be granted on the invention known as

(11) **Insert Identification such as Title, Case Number, or Foreign Application Number** (11) MANUFACTURING METHOD OF SEMICONDUCTOR DEVICE AND SUBSTRATE
PROCESSING APPARATUS

(Attorney Docket No. 127570)

for which the undersigned has (have) executed an application for patent in the United States of America on even date herewith or

(12) **Insert Date of Signing of Application** (12) _____
on _____

(13) **Alternative Identification for filed applications** (13) U.S. application Serial Number _____
filed April 28, 2006

1) Each undersigned agrees to execute all papers necessary in connection with any application and any continuing, divisional or reissue applications for the invention, and any patent(s) issuing thereon, and also to execute separate assignments in connection with such applications and patents as the Assignee may deem necessary.

2) Each undersigned agrees to execute all papers necessary in connection with any interference which may be declared concerning any application or continuation or division thereof, or any patent or reissue application based thereon, for the invention, and to cooperate with the Assignee in every way possible in obtaining evidence and going forward with such interference.

3) Each undersigned agrees to execute all papers and documents and perform any act which may be necessary in connection with claims or provisions of the International Convention for Protection of Industrial Property or similar agreements.

4) Each undersigned agrees to perform all affirmative acts which may be necessary to obtain, maintain or confirm by reissue or reexamination a grant of a valid United States patent to the Assignee.

5) Each undersigned authorizes and requests the Commissioner of the U.S. Patent and Trademark Office to issue any and all Letters Patents of the United States resulting from said application(s) to the said Assignee, as Assignee of the entire interest, and covenants that he has full right to convey the entire interest herein assigned, and that he has not executed, and will not execute, any agreements in conflict herewith, and agrees that this assignment is binding on him and his heirs, successors, assigns and legal representatives.

6) Each undersigned hereby grants the firm of **OLIFF & BERRIDGE, PLC** the power to insert on this assignment any further identification that may be necessary or desirable in order to comply with the rules of the United States Patent and Trademark Office for recordation of this document.

In witness whereof, executed by the undersigned on the date(s) opposite the undersigned name(s).

Date	<u>April 12, 2006</u>	Inventor Signature	<u>Atsushi Sano</u>	(SEAL)
Date	<u>April 12, 2006</u>	Inventor Signature	<u>Sadayoshi Horii</u>	(SEAL)
Date	<u>April 11, 2006</u>	Inventor Signature	<u>Hideharu Itatani</u>	(SEAL)
Date	<u>April 12, 2006</u>	Inventor Signature	<u>Masayuki Asai</u>	(SEAL)
Date	_____	Inventor Signature	_____	(SEAL)
Date	_____	Inventor Signature	_____	(SEAL)
Date	_____	Inventor Signature	_____	(SEAL)
Date	_____	Inventor Signature	_____	(SEAL)

This assignment should preferably be signed before: (a) a Notary Public if within the U.S.A. (b) a U.S. Consul if outside the U.S.A. If neither, then it should be signed before at least two witnesses who also sign here:

Date	_____	Witness	_____
Date	_____	Witness	_____